

Figures 27-37; and each of the reference numbers in Figures 27-37 have been amended to comport with amendments in the specification. The amendments to original Figures 1-11 are shown in red. Formal drawings reflecting these changes will be submitted in due course.

**IN THE CLAIMS:**

~~Please cancel claims 1-53 and please add the following new claims:~~

54. (New) An apparatus for processing a single wafer, such as a semiconductor wafer, a magnetic disk, or an optical disk, comprising:

a framework;

a processing bowl mounted to the framework, the processing bowl comprising an inner portion having an interior adapted to receive a pool of a processing chemical, an outer portion, and a fluid-receiving space between the inner portion and the outer portion;

a chemical supply adapted to supply the processing chemical to the processing bowl;

a processor head mounted for movement between at least one loading position and at least one processing position, the processor head in its loading position being adapted to position a wafer outside the interior of the inner portion, the processor head carrying a rotatable wafer support adapted to support a wafer within the interior of the inner portion when the processor head is in the processing position;

a second processing chamber; and

a wafer transfer adapted to move wafers to and from the processing bowl, and to and from the second processing chamber.

55. (New) An apparatus according to claim 54 wherein the wafer support extends downwardly to a height below an upper edge of the processing bowl when the processor head is in the processing position.